

**General Description**

- Trench Power MOSFET technology
- Low  $R_{DS(ON)}$
- Low Gate Charge
- RoHS and Halogen-Free Compliant

**Applications**

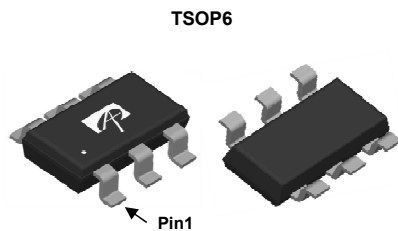
- Complementary MOSFET for DC FAN, Motor

**Product Summary**
**N-Channel**

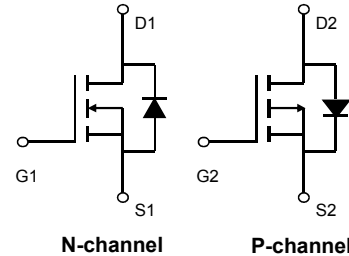
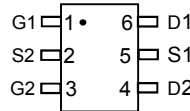
$V_{DS} = 30V$   
 $I_D = 3.5A$  ( $V_{GS} = 10V$ )  
 $R_{DS(ON)} < 50m\Omega$  ( $V_{GS} = 10V$ )  
 $< 70m\Omega$  ( $V_{GS} = 4.5V$ )

**P-Channel**

$-30V$   
 $-2.7A$  ( $V_{GS} = -10V$ )  
 $R_{DS(ON)} < 100m\Omega$  ( $V_{GS} = -10V$ )  
 $< 170m\Omega$  ( $V_{GS} = -4.5V$ )



Top View



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AO6602G	TSOP-6	Tape & Reel	3000

**Absolute Maximum Ratings  $T_A = 25^\circ C$  unless otherwise noted**

Parameter	Symbol	Max N-channel	Max P-channel	Units	
Drain-Source Voltage	$V_{DS}$	30	-30	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V	
Continuous Drain Current	$I_D$	$T_A = 25^\circ C$	3.5	-2.7	A
		$T_A = 70^\circ C$	3	-2.1	
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	20	-15		
Power Dissipation <sup>B</sup>	$P_D$	$T_A = 25^\circ C$	1.15	1.15	W
		$T_A = 70^\circ C$	0.73	0.73	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150		$^\circ C$	

**Thermal Characteristics**

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	78	110	$^\circ C/W$
Maximum Junction-to-Ambient <sup>A,D</sup>		Steady-State	106	150
Maximum Junction-to-Lead	$R_{\theta JL}$	64	80	$^\circ C/W$

**N-Channel Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			1 5	μA
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =250μA	1.5	2.0	2.5	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =3.5A T <sub>J</sub> =125°C		42 65	50 78	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A		56	70	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =3.5A		12		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =1A, V <sub>GS</sub> =0V		0.79	1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				1.5	A
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz		210		pF
C <sub>oss</sub>	Output Capacitance			35		pF
C <sub>riss</sub>	Reverse Transfer Capacitance			23		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		1.5		Ω
<b>SWITCHING PARAMETERS</b>						
Q <sub>g(10V)</sub>	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =3.5A		4.05		nC
Q <sub>g(4.5V)</sub>	Total Gate Charge			2		nC
Q <sub>gs</sub>	Gate Source Charge			0.55		nC
Q <sub>gd</sub>	Gate Drain Charge			1		nC
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =4.2Ω, R <sub>GEN</sub> =3Ω		4.5		ns
t <sub>r</sub>	Turn-On Rise Time			1.5		ns
t <sub>D(off)</sub>	Turn-Off DelayTime			18.5		ns
t <sub>f</sub>	Turn-Off Fall Time			1.5		ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time		I <sub>F</sub> =3.5A, dI/dt=100A/μs		7.5	
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =3.5A, dI/dt=100A/μs		2.5		nC

A. The value of R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> =25° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150° C, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150° C. Ratings are based on low frequency and duty cycles to keep initial T<sub>J</sub>=25° C.

D. The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, assuming a maximum junction temperature of T<sub>J(MAX)</sub>=150° C. The SOA curve provides a single pulse rating.

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N-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

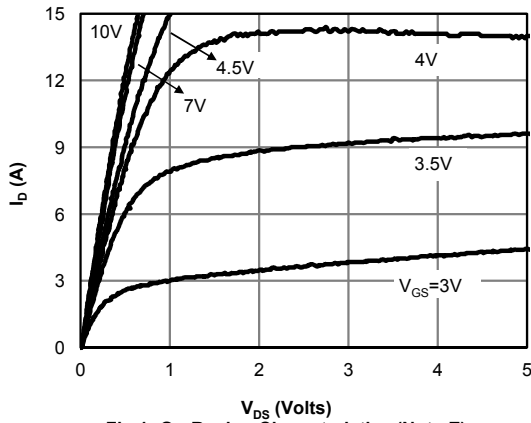


Fig 1: On-Region Characteristics (Note E)

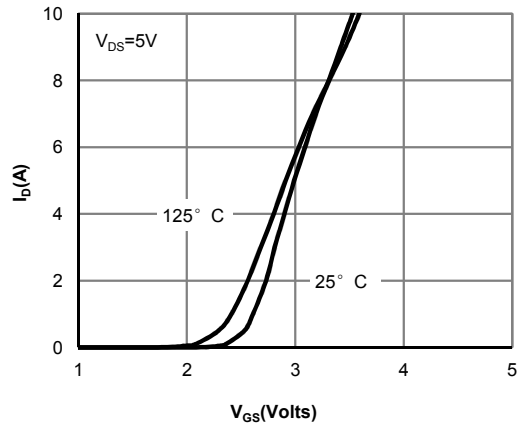


Figure 2: Transfer Characteristics (Note E)

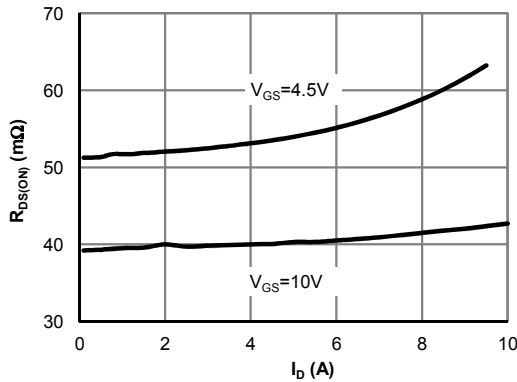


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

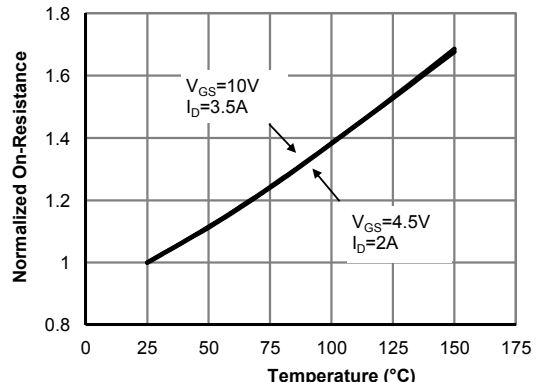


Figure 4: On-Resistance vs. Junction Temperature (Note E)

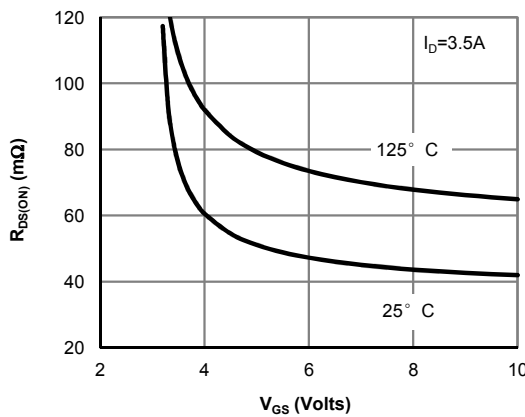


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

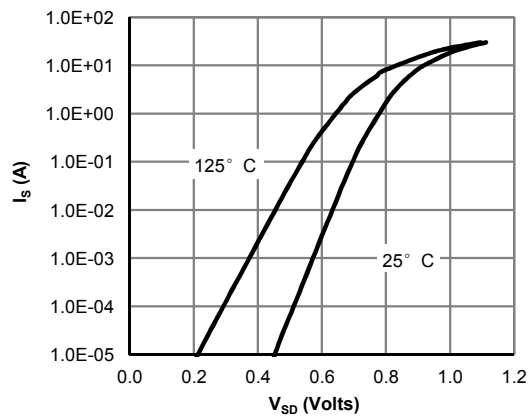


Figure 6: Body-Diode Characteristics (Note E)

N-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

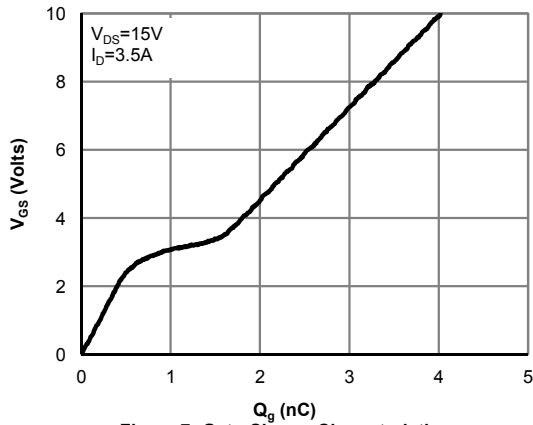


Figure 7: Gate-Charge Characteristics

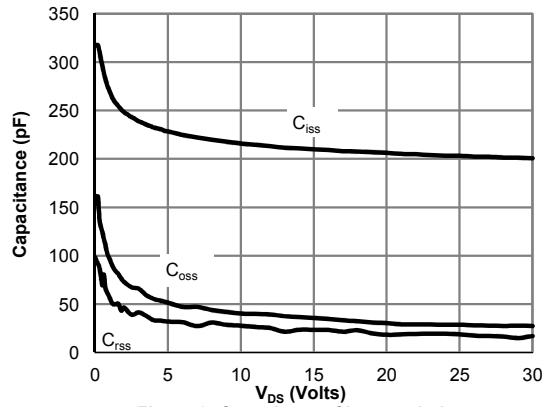


Figure 8: Capacitance Characteristics

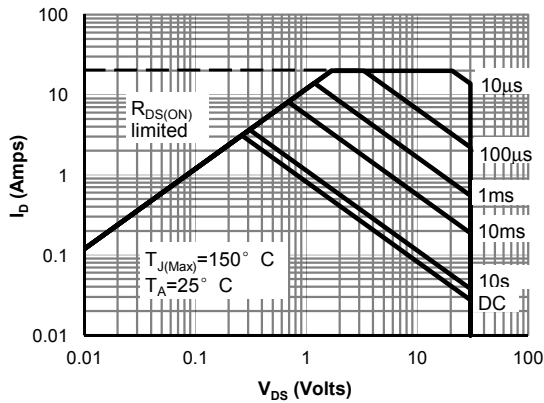


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

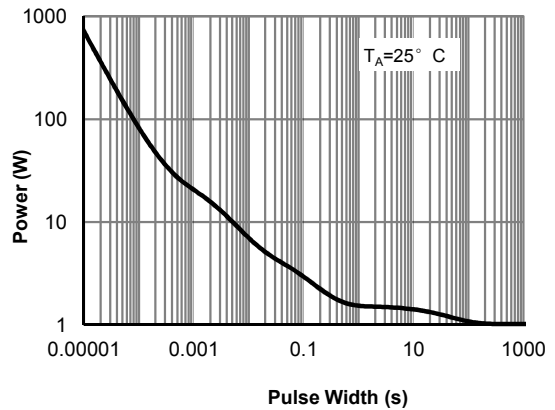


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

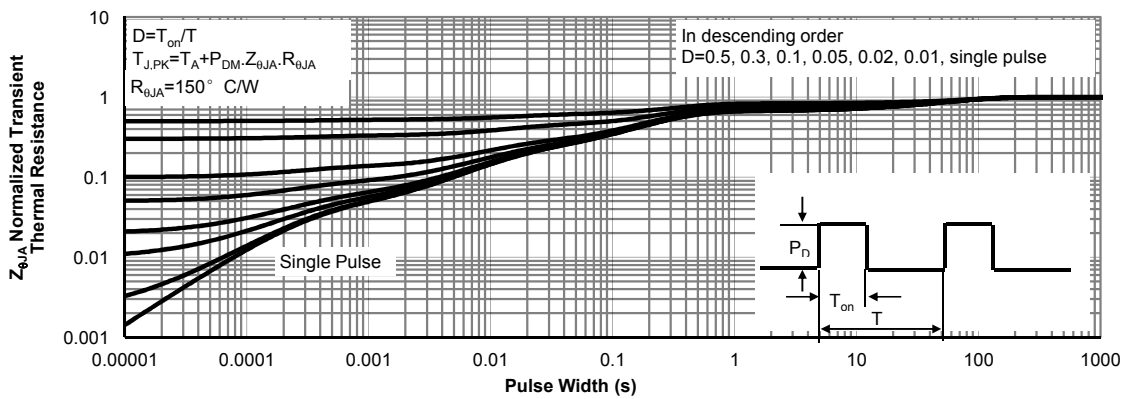
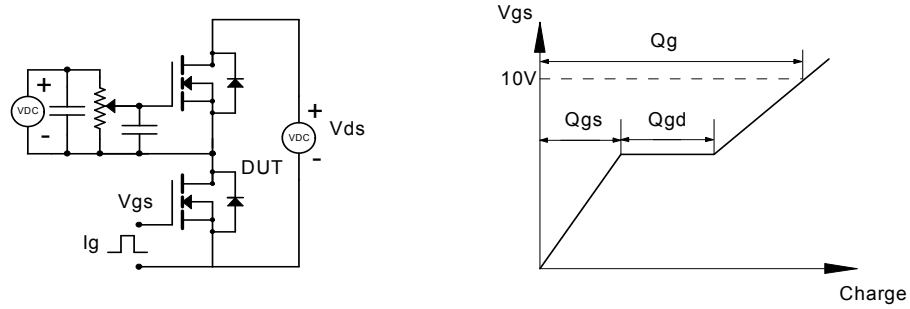
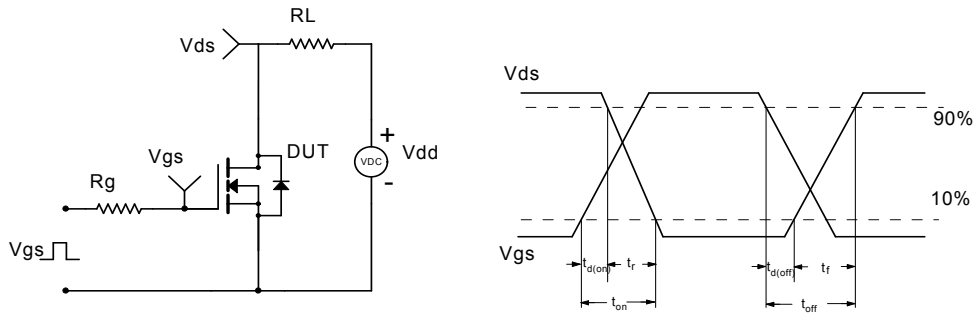


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

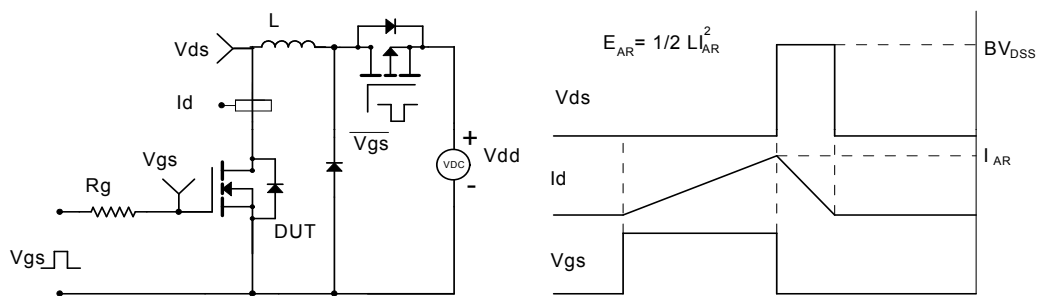
**Gate Charge Test Circuit & Waveform**



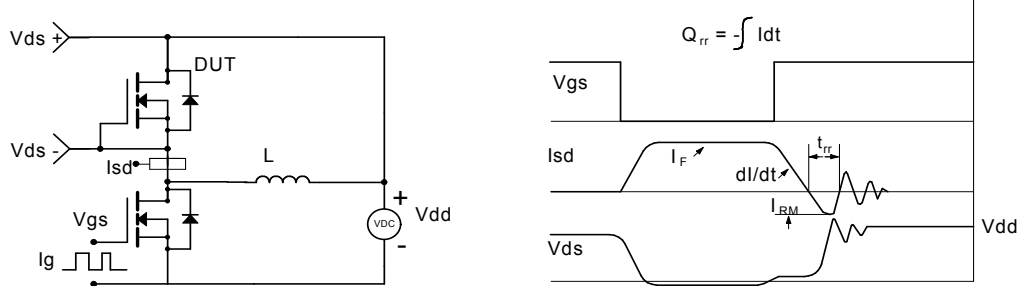
**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching (UIS) Test Circuit & Waveforms**



**Diode Recovery Test Circuit & Waveforms**



**P-Channel Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =-250μA, V <sub>GS</sub> =0V	-30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			-1 -5	μA
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =-250μA	-1.4	-1.9	-2.4	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-2.7A T <sub>J</sub> =125°C		82	100	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2A		115	140	
					130	170
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-2.7A		5.5		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V		-0.8	-1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				-1.5	A
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-15V, f=1MHz		210		pF
C <sub>oss</sub>	Output Capacitance			42		pF
C <sub>riss</sub>	Reverse Transfer Capacitance			26		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		5.3		Ω
<b>SWITCHING PARAMETERS</b>						
Q <sub>g(10V)</sub>	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =-15V, I <sub>D</sub> =2.7A		4.3		nC
Q <sub>g(4.5V)</sub>	Total Gate Charge			2.2		nC
Q <sub>gs</sub>	Gate Source Charge			0.7		nC
Q <sub>gd</sub>	Gate Drain Charge			1.1		nC
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> =10V, V <sub>DS</sub> =-15V, R <sub>L</sub> =5.55Ω, R <sub>GEN</sub> =3Ω		7.5		ns
t <sub>r</sub>	Turn-On Rise Time			4.1		ns
t <sub>D(off)</sub>	Turn-Off DelayTime			11.8		ns
t <sub>f</sub>	Turn-Off Fall Time			3.8		ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =-2.7A, dI/dt=100A/μs		11.3		ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =-2.7A, dI/dt=100A/μs		4.4		nC

A. The value of R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> =25° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150° C, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150° C. Ratings are based on low frequency and duty cycles to keep initial T<sub>J</sub>=25° C.

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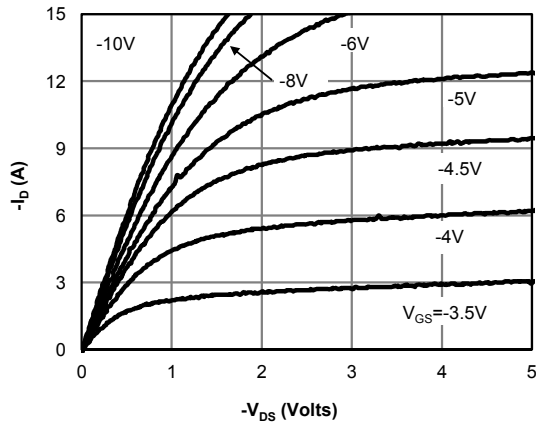


Fig 1: On-Region Characteristics (Note E)

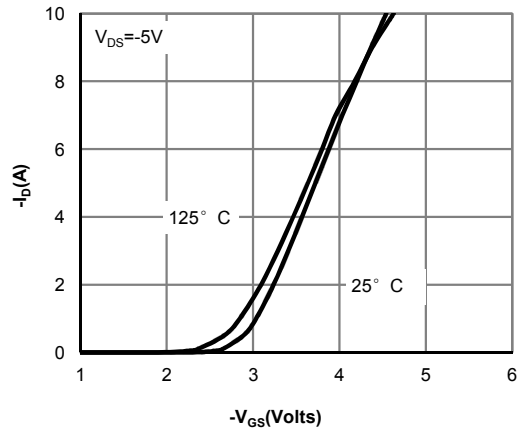


Figure 2: Transfer Characteristics (Note E)

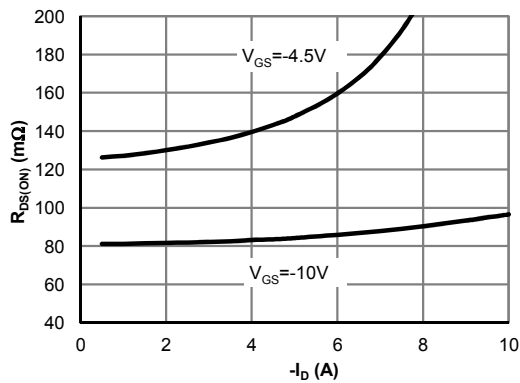


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

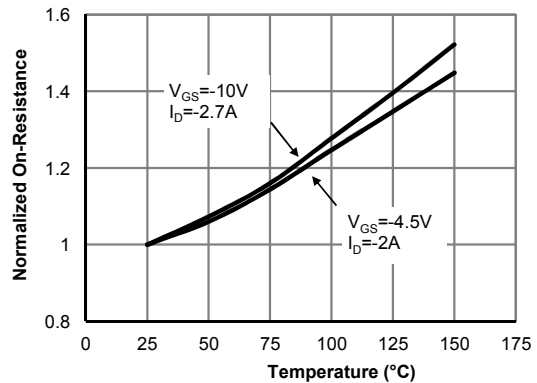


Figure 4: On-Resistance vs. Junction Temperature (Note E)

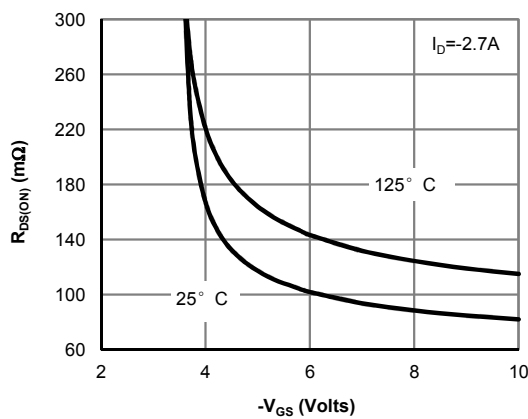


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

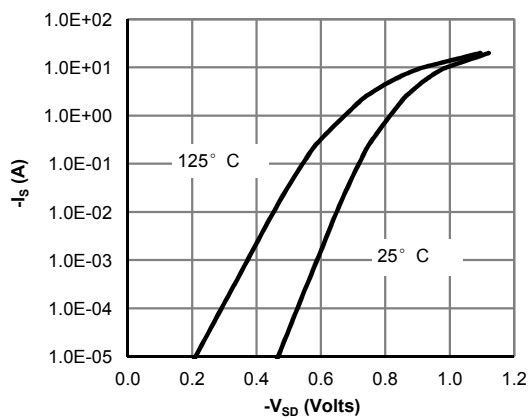


Figure 6: Body-Diode Characteristics (Note E)

P-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

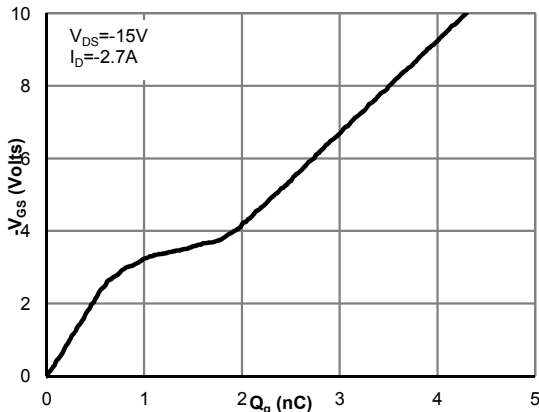


Figure 7: Gate-Charge Characteristics

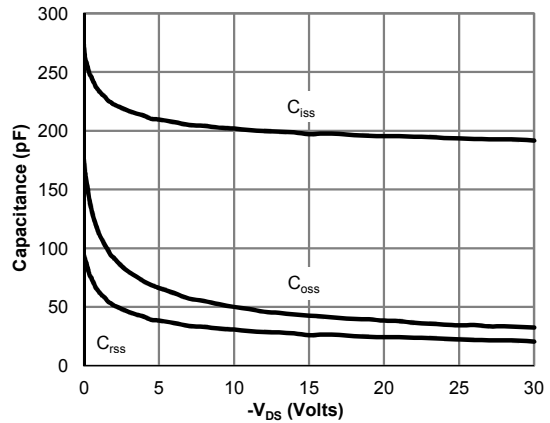


Figure 8: Capacitance Characteristics

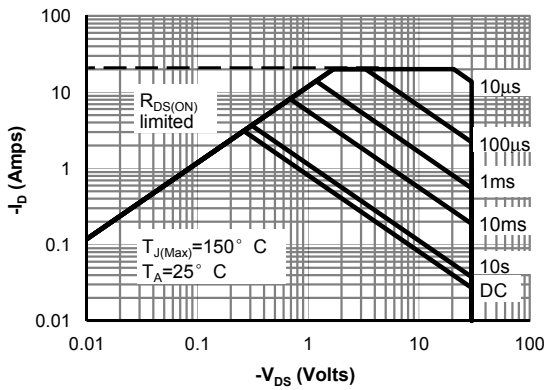


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

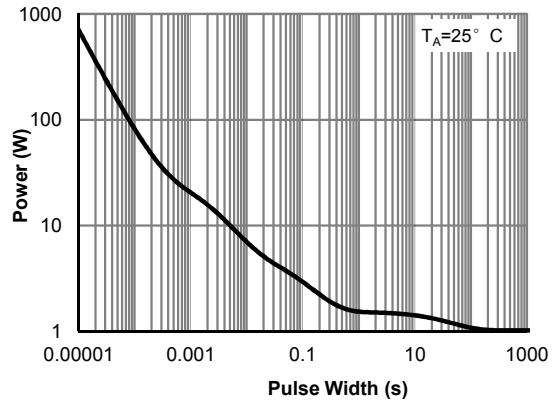


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

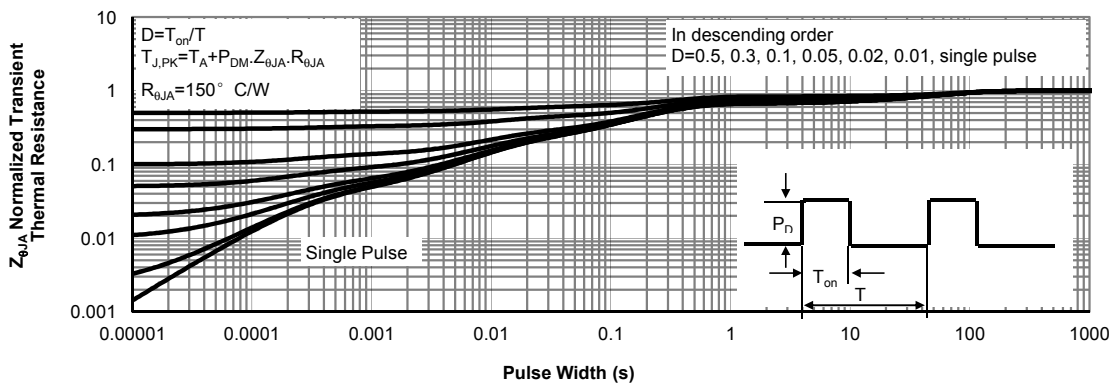
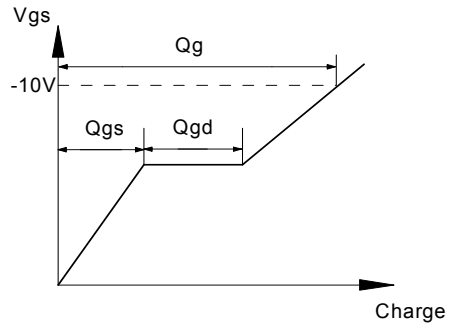
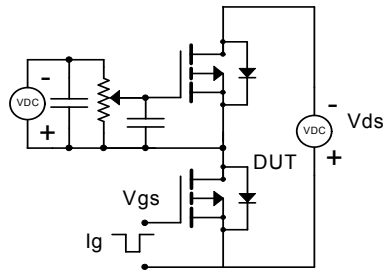


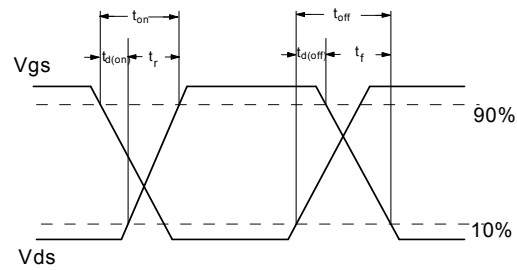
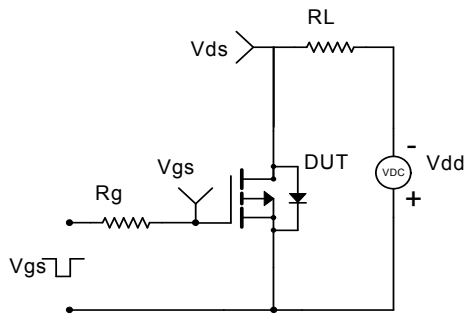
Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)



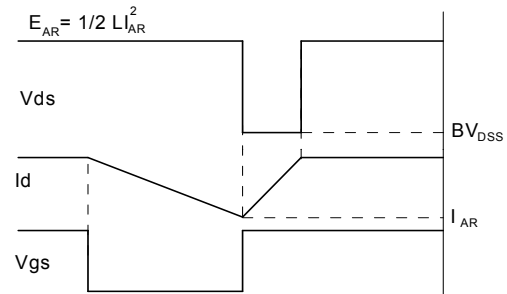
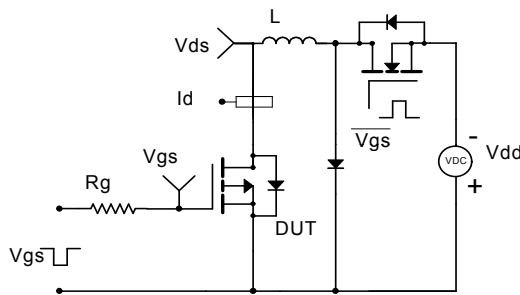
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

